

## Characteristic and moisture permeability of SiO<sub>x</sub>C<sub>y</sub> thin film synthesized by Atmospheric pressure-plasma enhanced chemical vapor deposition

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Atmospheric pressure- plasma enhanced chemical vapor deposition(AP-PECVD)Processes are recognized as promising and cost effective methods for wide-area coating on sheets of steel, glass, polymeric web, etc.

In this study, SiO<sub>x</sub>C<sub>y</sub> thin films were deposited by using AP-PECVD with a dielectric barrier discharge(DBD). The characteristic of SiO<sub>x</sub>C<sub>y</sub> thin films were investigated as a function of the HMDSO/O<sub>2</sub>/He flow rate. And the moisture permeability of SiO<sub>x</sub>C<sub>y</sub> thin films was studied. The SiO<sub>x</sub>C<sub>y</sub> thin films were characterized by the Fourier-transformed Infrared(FT-IR) spectroscopy and also investigated by X-ray photo electron spectroscopy(XPS), Auger Electron Spectroscopy(AES). The moisture permeability of SiO<sub>x</sub>C<sub>y</sub> thin films was investigated by H<sub>2</sub>O permeability tester

Detailed experimental results will be demonstrated through the present work.

### Keywords

AP-PECVD

DBD

SiO<sub>x</sub>C<sub>y</sub>

HMDS